



2N4300

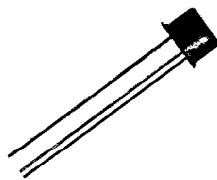
NPN EPITAXIAL PLANAR SILICON POWER TRANSISTORS

... for power-amplifier and high-speed-switching applications.

- 15 WATT @ 100°C CASE TEMPERATURE
- MAXIMUM $V_{CE(SAT)}$ = 0.3 VOLTS @ 1.0 AMP. I_C
- TYPICAL t_{ON} = 130 μ s @ 1.0 AMP. I_C
- MINIMUM f_T = 30 MHZ

NPN EPITAXIAL PLANAR SILICON POWER TRANSISTOR

TO-5



MAXIMUM RATINGS

| RATINGS | SYMBOL | 2N4300 | UNITS |
|---|----------------|-------------|--------------------------|
| Collector-Emitter Voltage ¹ | V_{CEO} | 80 | Vdc |
| Collector-Base Voltage | V_{CBO} | 100 | Vdc |
| Emitter-Base Voltage | V_{EBO} | 8.0 | Vdc |
| Collector Current -- Continuous Peak ² | I_C | 2.0 4.0 | Adc |
| Base Current -- Continuous | I_B | 1.0 | Adc |
| Emitter Current--Continuous | I_E | 3.0 | Adc |
| Total Power Dissipation @ $T_C = 25^\circ\text{C}^3$ Derate above 25°C^4 | P_D | 1.0 15 | W W/ $^\circ\text{C}$ |
| Operating & Storage Junction Temperature Range | T_J, T_{STG} | -65 to +200 | $^\circ\text{C}$ |
| Lead temperature $\frac{1}{4}$ inch from Case for 10 seconds | T_L | 230 | $^\circ\text{C}$ |

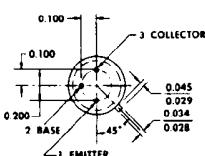
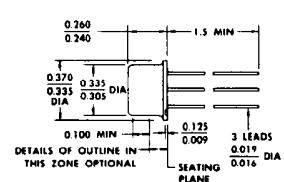
THERMAL CHARACTERISTICS

| CHARACTERISTICS | SYMBOL | MAX. | UNITS |
|--|-----------------|------|---------------------------|
| Thermal Resistance, Junction-to-Case | $R_{\theta JC}$ | 6.66 | $^\circ\text{C}/\text{W}$ |
| Thermal Resistance, Junction-to-Free-Air | $R_{\theta JA}$ | 175 | $^\circ\text{C}/\text{W}$ |

¹This value applies when the base-emitter diode is open-circuited. ³Derate linearly to 200°C free air temperature at the rate of 5.72 mW/ $^\circ\text{C}$

²This value applies for $t_p \leq 0.3$ ms, duty cycle $\leq 10\%$. ⁴Derate linearly to 200°C case temperature at the rate of 0.15 W/ $^\circ\text{C}$

MECHANICAL OUTLINE



THE COLLECTOR IS IN ELECTRICAL CONTACT WITH THE CASE.

ALL JEDEC TO-5 DIMENSIONS AND NOTES ARE APPLICABLE.

ALL DIMENSIONS ARE
IN INCHES
UNLESS OTHERWISE
SPECIFIED



2N4300

ELECTRICAL CHARACTERISTICS ($T_C = 25^\circ\text{C}$ unless otherwise noted)

| Characteristics | Symbol | Min | Max | Unit |
|--|-----------------------------|----------|---------------|--|
| OFF CHARACTERISTICS | | | | |
| Collector-Emitter Breakdown Voltage ⁵ $I_C = 30 \text{ mA}_\text{dc}, I_B = 0$ | $V_{(\text{BR})\text{CEO}}$ | 80 | | Vdc |
| Collector Cutoff Current $V_{CE} = 40 \text{ Vdc}, I_B = 0$ | I_{CEO} | | 1.0 | μA_dc |
| Collector Cutoff Current $V_{CE} = 90 \text{ Vdc}, V_{BE} = 0$ $V_{CE} = 90 \text{ Vdc}, V_{BE} = 0, T_C = 150^\circ\text{C}$ | I_{CES} | | 10 75 | μA_dc μA_dc |
| Emitter Cutoff Current $V_{EB} = 5.0 \text{ Vdc}, I_C = 0$ $V_{EB} = 8.0 \text{ Vdc}, I_C = 0$ | I_{EBO} | | 0.5 10 | μA_dc |
| ON CHARACTERISTICS ^{5 & 6} | | | | |
| Static Forward Current Transfer Ratio $I_C = 1.0 \text{ Adc}, V_{CE} = 2.0 \text{ Vdc}$ $I_C = 2.0 \text{ Adc}, V_{CE} = 2.0 \text{ Vdc}$ | h_{FE} | 30 15 | 120 | |
| Collector-Emitter Saturation Voltage $I_C = 1.0 \text{ Adc}, I_B = 100 \text{ mA}_\text{dc}$ $I_C = 2.0 \text{ Adc}, I_B = 200 \text{ mA}_\text{dc}$ | $V_{CE(\text{sat})}$ | | 0.3 0.5 | Vdc |
| Base-Emitter Voltage $I_C = 2.0 \text{ Adc}, V_{CE} = 2.0 \text{ Vdc}$ | V_{BE} | | 1.2 | Vdc |
| DYNAMIC CHARACTERISTICS | | | | |
| Forward Current Transfer Ratio $I_C = 1.0 \text{ Adc}, V_{CE} = 5.0 \text{ Vdc}, f = 1 \text{ kHz}$ | h_{fe} | 30 | | |
| Forward Current Transfer Ratio $I_C = 1.0 \text{ Adc}, V_{CE} = 10 \text{ Vdc}, f = 15 \text{ MHz}$ | $ h_{fe} $ | 2.0 | | |
| SWITCHING CHARACTERISTICS | | | | |
| Characteristics | Symbol | Typical | Units | |
| Turn-On Time | t_{on} | 0.13 | μs | |
| Turn-Off Time | t_{off} | 1.5 | μs | |

⁵These parameters must be measured using pulse techniques, $I_p = 300 \mu\text{s}$, duty cycle $\leq 2.0\%$.

⁶These parameters are measured with voltage-sensing contacts separate from the current-carrying contacts.

SX LEVEL RELIABILITY TESTING

| 100% SCREENING | GROUP A | GROUP B (Sample) | GROUP C (Sample) |
|-----------------------|---------------------------|-------------------------|-----------------------|
| Internal Visual | Visual and Mechanical | Solderability | Physical Dimensions |
| Temp Cycle | DC Static Tests 25°C | Temp Cycle | Thermal Shock |
| Thermal Response | DC Static Tests High Temp | Fine and Gross Leak | Terminal Strength |
| Constant Acceleration | DC Static Tests Low Temp | Bond Strength | Hermetic Seal |
| PIND | Dynamic Tests @ 25°C | Intermittent Op Life | Moisture Resistance |
| Fine and Gross Leak | | Steady State Op Life | Shock Test |
| HTRB | | Thermal Resistance | Vibration Test |
| Power Burn In | | Hi-Temp (non-operating) | Constant Acceleration |
| | | | Salt Atmosphere |
| | | | Operation Life |

NEW ENGLAND SEMICONDUCTOR

6 Lake Street Lawrence, MA 01841
1-800-446-1158 / (978) 794-1666 / FAX: (978) 689-0803

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